

Please amend the claims as indicated below:

1. (Currently amended) A method of processing an array of electronic components comprising the steps of:
providing mounting means;
mounting unsingulated electronic components onto the mounting means; then
singulating the components to physically separate them; and then
testing the singulated electronic components for defects while they are mounted on the mounting
means and without removal therefrom.
2. (Previously presented) A method according to claim 1, further comprising the step of
applying markings to distinguish non-defective ones of the electronic components from defective
ones after testing while they are still mounted on the mounting means.
3. (Original) A method according to claim 2, wherein the singulation, testing and marking
steps are carried out at two or more stations.
4. (Original) A method according to claim 3, including the step of moving the electronic
components at least between the testing and marking positions for testing and marking respectively.
5. (Previously presented) A method according to claim 1, which includes the step of
detecting the alignments of electronic components before testing, and orienting the array of
electronic components as desired before implementing testing.
6. (Previously presented) A method according to claim 2, wherein the markings are applied
with a laser device which generates a laser beam, for effecting marking.
7. (Currently amended) A method according to claim 6, wherein:
the mounting means comprises a film of laser transparent tape with an adhesive on one surface;

wherein each electronic component is mounted on the adhesive surface of the film of transparent tape; and

marking is effected by passing the laser beam generated by the laser device through the film of laser transparent tape toward the adhesive surface thereof,

the surface of the electronic component being marked being the one in contact with the adhesive surface of the tape.

8. (Currently amended) An apparatus for processing an unsingulated array of electronic components comprising:

a mounting means for mounting an unsingulated array of electronic components;

a singulating device for singulating the said array of electronic components; and

a testing device operative to test each of the said singulated electronic components for defects;

whereby singulation and testing of singulated electronic components are conducted while they are mounted on the mounting means without removal therefrom.

9. (Previously presented) An apparatus according to claim 8, including an inscribing device for applying markings to distinguish defective and non-defective tested electronic components while they are mounted on the mounting means.

10. (Original) An apparatus according to claim 9, wherein the singulation, testing and marking are carried out at two or more stations of the apparatus.

11. (Previously presented) An apparatus according to claim 10, including moving means for moving the electronic components for processing at least between the testing and marking positions.

12. (Original) An apparatus according to claim 11, wherein the moving means is adapted to move the electronic components in linear and rotary axes, such as an XYZ-Theta table.

13. (Original) An apparatus according to claim 8, wherein the mounting means comprises a film of material having an adhesive on one side and stretched on a support frame, whereby electronic components are mountable on the adhesive side.

14. (Original) An apparatus according to claim 13, wherein there is a vacuum chuck for holding in position the support frame and film on which electronic components are mountable, during the singulation, testing and marking.

15. (Previously presented) An apparatus according to claim 8, including an orienting device to adjust alignment of electronic components and/or to locate the positions of defective components.

16. (Previously presented) An apparatus according to claim 15, wherein the orienting device is an image recognition vision system.

17. (Original) An apparatus according to claim 9, wherein the inscribing device is a laser device which generates a laser beam to mark a surface of an electronic device by heating said surface.

18. (Currently amended) An apparatus according to claim 17, wherein: the mounting means comprises a film of transparent tape with an adhesive surface on which electronic components are mountable; and the laser device is operative to direct the laser beam generated ~~thereby~~ through ~~thereby~~ through the film toward the adhesive surface thereof to mark electronic components mounted on said adhesive surface.

19. (Original) An apparatus according to claim 18, including an inverting device to invert the transparent tape to expose the surface of each electronic component that is mounted on said adhesive surface of the transparent tape to the laser device for marking.

20. (Previously presented) A method according to claim 1, wherein the electronic components comprise molded semiconductor packages.

21. (Previously presented) An apparatus according to claim 8, wherein the electronic components comprise molded semiconductor packages.